

Fig. 1

- Series 850 single and double row interconnects have .050" pin spacing & permit board stacking as low as .248".
- Pin headers have .016" dia. pins (MM #4006-0). See page 175 for details.
- MM #0467 and MM #4890 receptacles use Hi-Rel, 3-finger BeCu #11 contacts rated at 3 amps. (#11 contact accepts pin diameters from .015"-.020"). See pages 129 and 131 for details.
- Insulators are high temp. thermoplastic, suitable for all soldering operations.

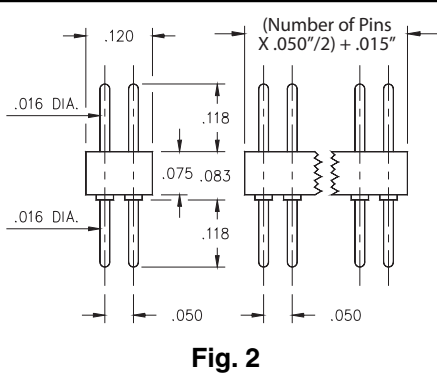
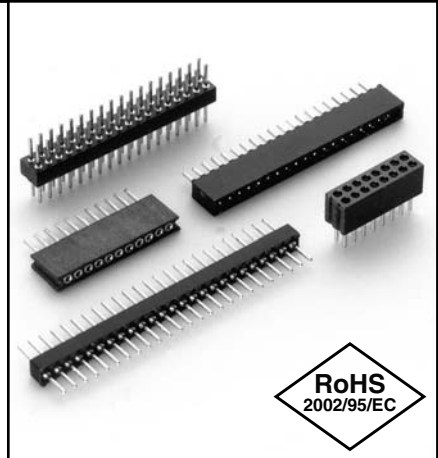


Fig. 2

Ordering Information

Fig. 1	Single Row	.087" Profile Pin Header
	850-XX-0__-10-001000	
	Specify # of pins	01-50
Fig. 2	Double Row	.075" Profile Pin Header
	852-XX-__-10-001000	
	Specify # of pins	002-100

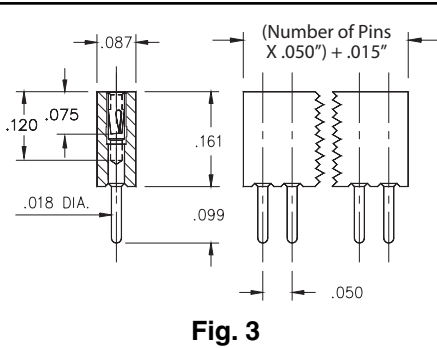


Fig. 3

For Electrical, Mechanical & Environmental Data, See pg. 4

XX=Plating Code See Below

For RoHS compliance select \diamond plating code.

SPECIFY PLATING CODE XX=	10 \diamond	90	40 \diamond	
Pin Plating	10 μ " Au	200 μ " Sn/Pb	200 μ " Sn	

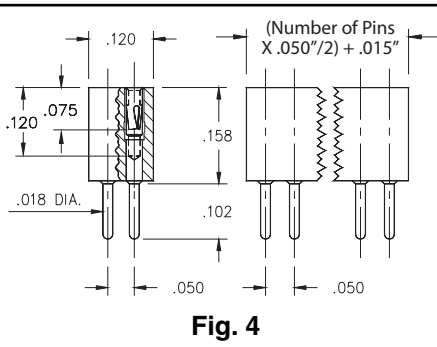


Fig. 4

Fig. 3	Single Row	.161" Profile Socket
	851-XX-0__-10-001000	
	Specify # of pins	01-50
Fig. 4	Double Row	.161" Profile Socket
	853-XX-__-10-001000	
	Specify # of pins	002-100

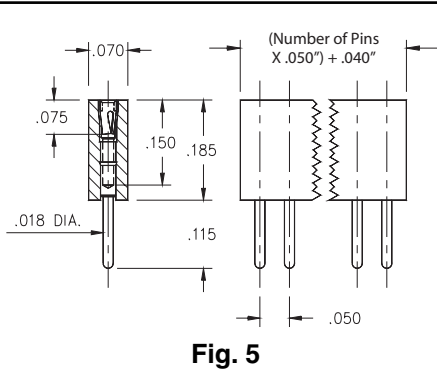


Fig. 5

Fig. 5	Single Row	.185" Profile Socket
	851-XX-0__-10-002000	
	Specify # of pins	01-77

For Electrical, Mechanical & Environmental Data, See pg. 4

XX=Plating Code See Below

For RoHS compliance select \diamond plating code.

SPECIFY PLATING CODE XX=		93	99		43 \diamond
Sleeve (Pin)		200 μ " Sn/Pb	200 μ " Sn/Pb		200 μ " Sn
Contact (Clip)		30 μ " Au	200 μ " Sn/Pb		30 μ " Au